ABSTRACT OF THE DISCLOSURE

A low temperature sinterable dielectric ceramic composition, as well as a multilayer ceramic chip capacitor and a ceramic electronic device. The dielectric ceramic composition comprises a major composition represented by the general formula: $x\{\alpha\ BaO, (1-\alpha)SrO\}-y\{SiO_2\}-z\{(1-\beta)ZrO_2, \beta\ Al_2O_3\}$ (wherein x, y and z are weight percentages; x+y+z=100, $55 \leq x \leq 75$, $10 \leq y \leq 35$, and $5 \leq z \leq 30$, α and β are moles; $0.4 \leq \alpha \leq 0.8$, and $0.01 \leq \beta \leq 0.07$) and 2 to 10 parts by weight of a Zn-B-silicate glass composition, per 100 parts by weight of the major composition. The multilayer ceramic chip capacitor and a multilayer ceramic circuit board for the electronic device comprise a plurality of dielectric ceramic layers, internal electrodes arrayed inside the dielectric ceramic layers, and outer electrodes electrically connected to the internal electrodes, characterized in that the dielectric ceramic layer is a sintered body of the dielectric ceramic composition mentioned above, and the internal electrode is made of a conductive base metal material.